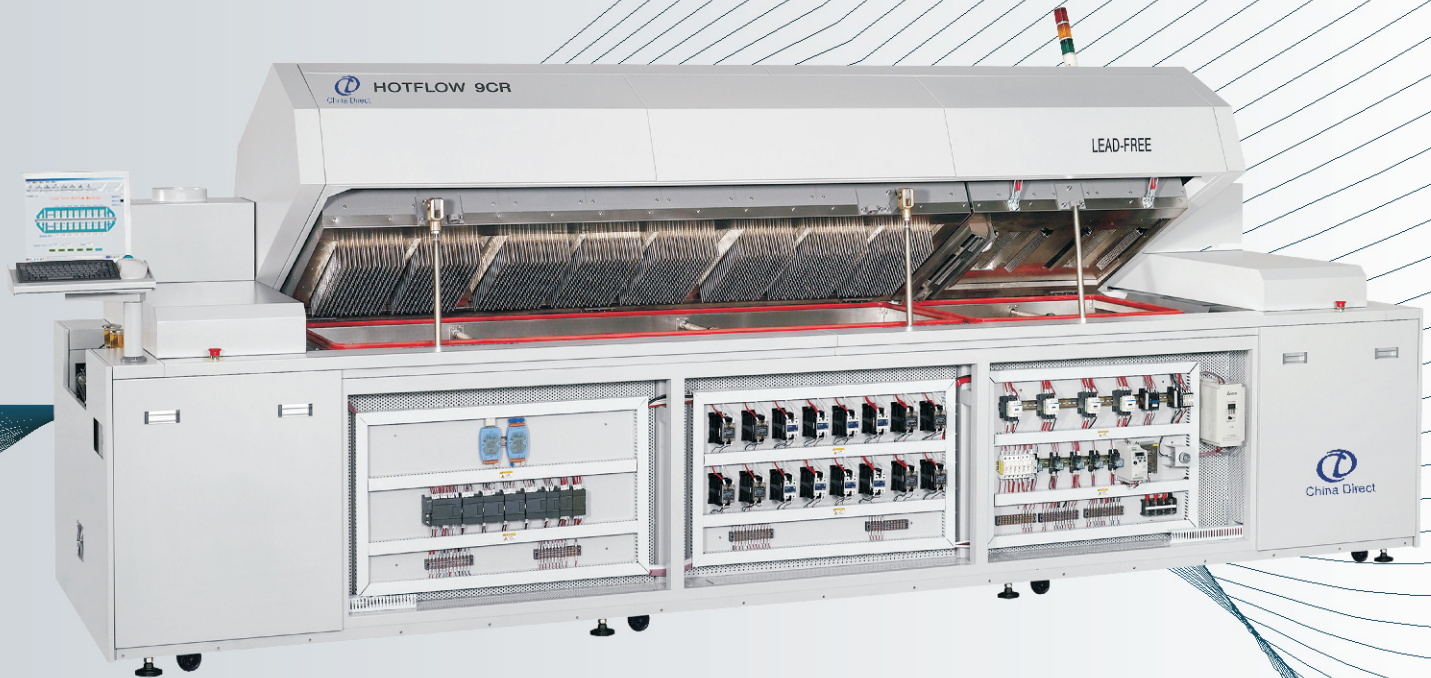




China Direct



Lead Free “Nozzle Jet” Reflow Oven

- Nozzle Jet/multi-jet technology for precise reflow results
- 8/10/12 zone configurations
- Dual control (touch screen back up if PC fails)
- Flux management standard on all configurations
- Excellent English operating interface for simple programming
- (3) thermocouple inputs for reflow profile creation
- Edge rail & mesh combo to accommodate all PCB requirements
- Smart edge rail entry oil feature
- Meets ALL CE standards for electrical and manufacturing
- Full documentation (schematics, assy drawings, ops manual)
- Built like a tank with clean electrical and mechanical mfg

Product Description



Specifications

Features

	Hotflow 8CR	Hotflow 10CR
Type of Solder	Lead free/standard	Lead free/standard
Max PCB Width	460mm (18")	460mm (18")
Component Types	BGA, CSP, 0201 Chip	BGA, CSP, 0201 Chip
Heating/cooling Zones	H=8 top/bottom C=2 top/bottom	H=10 top/bottom C=3 top/bottom
Temperature Accuracy	+/- 1°C	+/- 1°C
PCB Temperature Deviation	+/- 2°C	+/- 2°C
Mesh Width	480mm	480mm
Transport Method	Edge rail and mesh	Edge rail and mesh
Conveyor Direction	Std: L > R (option R > L)	Std: L > R (option R > L)
Conveyor Height	940mm +/- 20mm	940mm +/- 20mm
Conveyor Speed	0 – 1800mm/min	0 – 1800mm/min
Temperature Control	P.I.D. Control	P.I.D. Control
Temp Control Range	Room Temp > 350°C	Room Temp > 350°C
Warm Up Time	< 25 minutes	< 25 minutes
Temp Stabilizing Time	< 5 minutes	< 5 minutes
Power Consumption Start > Normal	53kW > 10.5kW	68kW > 12kW
System Control	Computer	Computer
Voltage Transformer	380V > 220V (North/South America)	380V > 220V (North/South America)
Dimensions (L x W x H)	5000 x 1350 x 1550mm	5900 x 13500 x 1550mm
Power Requirement	3 phase, 220V	3 phase, 220V
Weight	1860kg	2150kg
Air Pressure	5-7 Kg/cm ²	5-7 Kg/cm ²